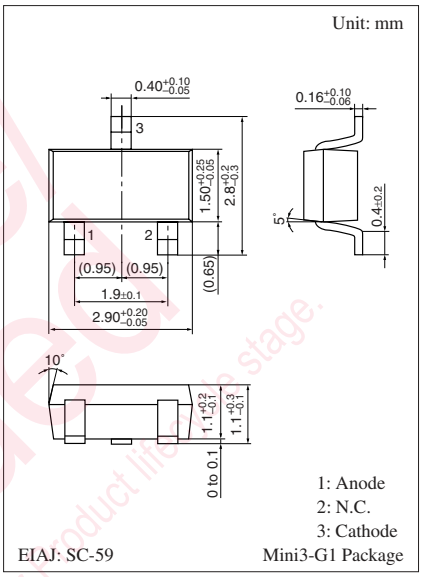
MA3X158 (MA158)

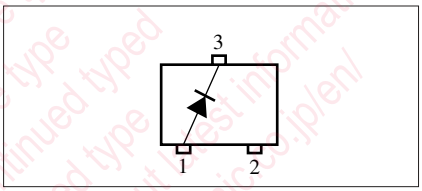
Silicon epitaxial planar type

For small power rectification and surge absorption



Marking Symbol: M1C

Internal Connection



■ Features

- High reverse voltage V_R
- Large forward current (Average) $I_{F(AV)}$
- Automatic mounting is possible

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Repetitive peak reverse voltage	V_{RRM}	250	V
Non-repetitive peak reverse surge voltage	V_{RSM}	300	V
Output current	I_O	100	mA
Repetitive peak forward current	I_{FRM}	225	mA
Non-repetitive peak forward surge current*	I_{FSM}	500	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) ∗: t = 1 s

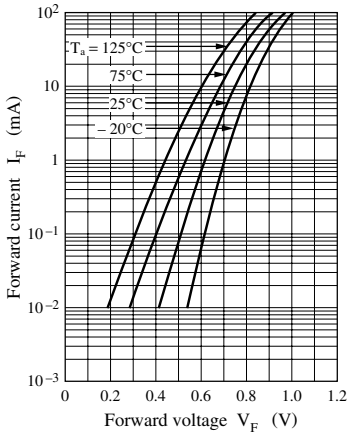
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 100 mA			1.3	V
Reverse current	I_R	V_R = 200 V			1.0	µA

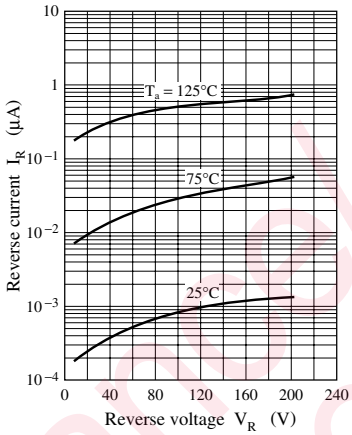
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 3 MHz.

Note) The part number in the parenthesis shows conventional part number.

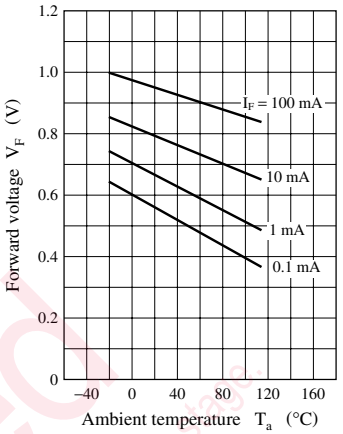
I_F — V_F



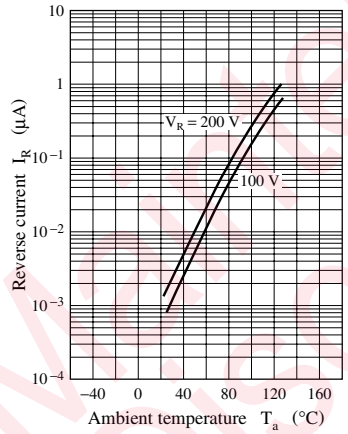
I_R — V_R



V_F — T_a



I_R — T_a



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